CLAIMS

1. A composite sheet for forming a protective film, comprising:

a support sheet;

a protective film-forming film which is laminated on the first surface side of the support sheet; and

a release sheet which is laminated on the protective film-forming film,

wherein an arithmetic mean roughness (Ra1) of a second surface of the support sheet is 0.47 μm or greater, and

an arithmetic mean roughness (Ra2) of the second surface of the support sheet after the support sheet is heated for 2 hours at 130°C is 0.25 μm or less.

2. The composite sheet for forming a protective film according to Claim 1,

wherein the support sheet is formed of a base material and an adhesive layer laminated on one surface of the base material and on the first surface side of the support sheet, or formed of a base material.

3. The composite sheet for forming a protective film according to Claim 2,

wherein the base material has a melting point of 90°C to 180°C.

4. The composite sheet for forming a protective film according to Claim 2 or 3,

wherein the base material has a storage elastic modulus of 1 to 100 MPa at 130°C.

5. The composite sheet for forming a protective film according to any one of Claims 2 to 4,

wherein the light transmittance of the base material at a wavelength of 1064 nm after the heating is 40% or greater.

6. The composite sheet for forming a protective film according to any one of Claims 2 to 5,

wherein the light transmittance of the base material at a wavelength of 532 nm after the heating is 40% or greater.

7. The composite sheet for forming a protective film according to any one of Claims 2 to 6,

wherein the base material is a film formed of a copolymer of ethylene and propylene.

8. The composite sheet for forming a protective film according to any one of Claims 1 to 7, further comprising:

an adhesive layer for a tool which is laminated on a peripheral portion of the protective film-forming film on the side opposite to the support sheet.

9. The composite sheet for forming a protective film according to any one of Claims 1 to 8,

wherein the protective film-forming film is a layer for forming a protective film for a semiconductor wafer or a semiconductor chip obtained by subjecting the semiconductor wafer to dicing.